

Small N₂ Reflow Oven for Lead-Free Soldering ECO-Reflow SNR-615

An advanced compact reflow oven for semiconductor packaging, hybrid components, and solder formation of SMT assemblies.



■ Features:

- Far infrared ray panel heaters and convection blow heating system achieve a minimized ΔT .
- Individual heater temperature settings provide high degree of freedom in a trapezoidal profile setting
Top and bottom heating system offers high degree of reproducibility in reflow profile.
- Air tight muffle structure furnace features 100 ppm or less oxygen concentration.
Low nitrogen consumption of 100 ppm at 200 liter/min attainable in every zone.
(Component's height is under 10 mm)
- New flux recovery mechanism at heating zone [Option]
Recovered flux is automatically collected after an operation is completed.
- Energy-saving design.
Highly efficient adiabatic structures reduce electric power consumption.
- Suitable for high temp. reflow (max. 350°C)

■ SNR-625 Standard Specification

● Dimensions	2,670 mm(L) x 1,100 mm(W) x 1,340 mm(H)	● PCB access	Width: 50 to 150mm, Length: 100 to 300mm
● Conveyor speed	0.1 to 1.0 m/min. (Variable)	● PCB access height	Upper: 10 to 20mm, Under: 5mm
● Pass line	900 ± 20mm	● Operating control	PLC + Microcomputer
● Heater system	Far infrared panel heaters and hot air convective blowers used in combined (6 heating zones)	● Weight	1,700kg (Approx.)
● Cooling unit	Top-and-bottom blast cooling by nitrogen gas	● Options	Customer-specified color, automatic width adjuster, flux automatic recovery mechanism, oxygen automatic concentration control, and others.
● Power supply (Max.)	200 VAC, 43kW, 3-phase		

★ Please call us for further details and technical information. As a leading manufacturer of soldering flux and soldering related materials, we would be pleased to provide advanced solutions in soldering technology. Design and specifications of system and equipment are subject to change without notice.

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■ Headquarters:

■ Sales Dept.: